EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L5	3	(29/852).ccls. and substrate and (porous adj (sheet or layer or film)) and hole and (conductive adj paste) and (resin adj layer) and ((release adj (film or layer)) with peel$3) and (((metal or copper) adj foil) with heat$3 or press$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 11:37
L6	3	(29/842,844,846,851).ccls. and substrate and (porous adj (sheet or layer or film)) and hole and (conductive adj paste) and (resin adj layer) and ((release adj (film or layer)) with peel$3) and (((metal or copper) adj foil) with heat$3 or press$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 11:38
L7	2	(174/258,264).ccls. and substrate and (porous adj (sheet or layer or film)) and hole and (conductive adj paste) and (resin adj layer) and ((release adj (film or layer)) with peel$3) and (((metal or copper) adj foil) with heat$3 or press$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 11:38
L8	4	(428/209,304.4,321.3).ccls. and substrate and (porous adj (sheet or layer or film)) and hole and (conductive adj paste) and (resin adj layer) and ((release adj (film or layer)) with peel$3) and (((metal or copper) adj foil) with heat$3 or press$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 11:39
S1	20	(kawakita-yoshihiro).in.	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/02/10 14:35
S2	18	(kawakita-yoshihiro).in. and (circuit adj board)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/02/10 14:36
S3	3	(kawakita-yoshihiro).in. and (circuit adj board adj electrically adj insulating adj material)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/02/10 14:37
S4	14	(("5,484,647") or ("5,851,646") or ("5,972,482") or ("4,383,363") or ("4,967,314") or ("6,326,694") or ("6,323,439") or ("6,251,502") or ("5,919,546") or ("5,473,119") or ("5,346,750") or ("5,652,042") or ("5,776,616") or ("5,639,528") or ("5,677,393")).PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2006/04/27 15:40

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S5	15	(("5,484,647") or ("5851646") or ("5,972,482") or ("4,383,363") or ("4,967,314") or ("6,326,694") or ("6,323,439") or ("6,251,502") or ("5,919,546") or ("5,473,119") or ("5,346,750") or ("5,652,042") or ("5,776,616") or ("5,639,528") or ("5,677,393")).PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2006/04/27 15:46
S6	1	("6734375").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2006/04/27 15:46
S7	92	("5484647").URPN.	USPAT	OR	ON	2006/04/27 16:32
S8	2	"6734375"	USPAT	OR	ON	2006/04/27 16:32
S9	1	("5346750").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/27 16:43
S10	1	("6596381").PN.	US-PGPUB; USPAT; IBM_TDB	OR	OFF	2006/04/27 16:44
S11	8	substrate and prepreg and hole and (conductive adj paste) and (resin adj layer) and ((release adj (film or layer)) with peel$3) and (((metal or copper) adj foil) with heat$3 or press$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:15
S12	6	("5817404" | "5837155" | "6127633" | "6217988" | "6320140" | "6329610").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/28 08:12
S13	10	substrate and (porous adj (sheet or layer or film)) and hole and (conductive adj paste) and (resin adj layer) and ((release adj (film or layer)) with peel$3) and (((metal or copper) adj foil) with heat$3 or press$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 11:36
S14	7	("5346750" | "5480503" | "5481795" | "5484647" | "5498467" | "5576519" | "5744758").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/28 08:35
S15	10	substrate and (porous adj (sheet or layer or film)) and hole and (conductive adj paste) and (resin adj layer) and ((release adj (film or layer)) with peel$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:38
S16	31	substrate and (porous adj (sheet or layer or film)) and hole and (conductive adj paste) and (resin adj layer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:51

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S17	7	("5851646" | "6033765" | "6121171" | "6125531" | "6197407" | "6270607" | "6323436").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2006/04/28 08:45
S18	789	(porous adj (sheet or layer)) and (resin adj layer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:47
S19	33	(porous adj (sheet or layer)) and (conductive adj paste) and (resin adj layer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:49
S20	789	(porous adj (sheet or layer)) and (resin adj layer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:50
S21	415	(porous adj (sheet or layer or film)) and hole and (resin adj layer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:56
S22	268	substrate and (porous adj (sheet or layer or film)) and hole and (resin adj layer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:52
S23	35	(porous adj (sheet or layer or film)) and hole and (conductive adj paste) and (resin adj layer)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 08:52
S24	55	(porous adj (sheet or layer or film)) and hole and (resin adj layer) and (PCB or (circuit adj board))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 09:07
S25	42	(porous adj (sheet or layer or film)) and hole and (resin adj layer) and (PCB or (circuit adj board)) and (press$3 same heat$3)	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 09:11
S26	42	(porous adj (sheet or layer or film)) and hole and (resin adj layer) and (PCB or (circuit adj board)) and ((pressed or pressing or pressure or press) same (heated or heat or heating))	US-PGPUB; USPAT; IBM_TDB	OR	ON	2006/04/28 09:12